

**Source: CWTS**

**Title: Completion of TDD integration in R'00**

**Agenda item: 5.2**

**Document for:**

Decision	<b>X</b>
Discussion	
Information	

## **1 Introduction**

The standard procedure in 3GPP has made great achievements due to the constructive works in all TSGs and WGs. The R'99 goal is achieved and the R'00 work has made very good progress. The integration of low chip rate TDD was discussed and approved as one of the features in R'00 in RAN#6 and RAN#7. Also in SA#6, the integration of low chip rate TDD was approved to be included in R'00. Since those meetings, a large amount of work has been carried out in TSG RAN and TSG RAN WGs. In TSG RAN WG1, the work for TR on low chip rate TDD is completed and specification phase of physical layer integration has started. For the layer2/layer3 (RAN2), Iu interface (RAN3) and RF(WG4), works have been started. But there remains big amount of work, which will need the co-ordination between TSG RAN and other TSGs, and also among TSG RAN WGs. As the organization partner, CWTS is paying much attention on the progress of low chip rate TDD integration work. The Chinese operators are also willing to see the completion of the low chip rate TDD integration work in R'00 to fit their commercialization requirements.

## **2 Proposals**

- TDD integration should be finalized in R'00.
- Due to the time limitation CWTS encourage the 3GPP TSGs to make much efforts to complete the low chip rate TDD integration in R'00 based on the agreed TRs and in line with RAN#6 and RAN#7 decision.